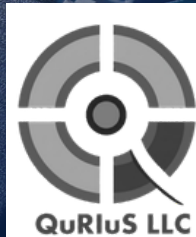


TECHNICAL LEADERSHIP FOR ADVANCED PACKAGING QUALITY AND RELIABILITY



**Building Technical Leadership Skills for the
Semiconductor Industry**



Center for Semiconductor
Manufacturing

When

November 2-4, 2026

Where

University of Arizona
Scottsdale Center

A focused three-day learning journey that will advance participants' technical expertise and capacity for leading and evaluating quality and reliability initiatives in advanced packaging operations.

Who Should Attend?



Why Attend

- Understand technical challenges related to product qualification
- Review quality assessment methodologies and statistical tools for performance evaluation
- Take a deep dive into reliability evaluation methodologies based on physics-of-failure and statistical modeling.

Investment

\$3,000

U of A alumni
discount available



**Interested in learning
more?**

Scan the QR code to
see when our next
cohort begins.

Example Program Agenda

DAY ONE

Examination of packaging baselines and technology trends.

Introduction to foundational terminologies, failure models, application-specific goals, Q&R metrics over product life cycle.

DAY TWO

Quality assessment methodologies, and the attendant statistical tools for performance evaluation.

Part I: Reliability evaluation methodologies based on physics of failure and statistical modeling.

DAY THREE

Part II: Reliability evaluation methodologies based on physics of failure and statistical modeling

Integration of advanced concepts - feature redundancy, canary circuits, digital twins, AI applications, predictive analytics and more.

Meet Your Facilitators



Shalabh Tandon is an executive leader with three decades of expertise in semiconductor product development and yield optimization to deliver reliable products in complex segments such as IoT, automotive, and high-performance computing. With a PhD in Polymer Science and Engineering, he has a distinguished track record of leading complex technical initiatives to enable advanced packaging. Throughout his career, he has been a key influencer among senior executives, technical fellows, and customer stakeholders to advocate for reliability.



Shubhada Sahasrabudhe is a technical leader with a distinguished career in semiconductor yield, quality, and reliability, with expertise in disruptive innovation. With more than 25 years of experience in advanced packaging technology and product development, she has played a pivotal role in aligning industry-wide quality strategies to enable AI infrastructure hyper-scaling. With a master's degree in mechanical engineering, Shubhada has an extensive track record in statistical modeling, testing methodologies, and customer quality management, making her an invaluable asset in driving technological and business innovation.